

68V N-Channel Enhancement Mode MOSFET

Description

The SX80N07T uses advanced trench technology to provide excellent R_{DS(ON)}, low gate charge and operation with Hight EAS. This device is suitable for use as a Battery protectionor in other Switching application.

General Features

V_{DS} = 68V I_D =80A

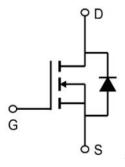
 $R_{DS(ON)} < 9.0 m\Omega$ @ $V_{GS}=10V$

Application

Battery protection

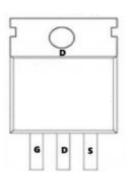
Load switch

Uninterruptible power supply









Absolute Maximum Ratings (T_c=25[°]C unless otherwise noted)

| Symbol | Parameter | Rating | Units |
|--------------------|--|------------|-------------------------|
| VDS | Drain-Source Voltage | 68 | V |
| VGS | Gate-Source Voltage | ±20 | V |
| l b@Tc=25℃ | Continuous Drain Current, V _{GS} @ 10V ¹ | 80 | Α |
| l b@Tc=100℃ | Continuous Drain Current, V _{GS} @ 10V ¹ | 52 | Α |
| IDM | Pulsed Drain Current ² | 320 | А |
| EAS | Single Pulse Avalanche Energy ³ | 110 | mJ |
| IAS | Avalanche Current | 22 | Α |
| P @Tc=25℃ | Total Power Dissipation ⁴ | 103 | W |
| TSTG | Storage Temperature Range | -55 to 150 | $^{\circ}\! \mathbb{C}$ |
| TJ | Operating Junction Temperature Range | -55 to 150 | $^{\circ}$ |
| R₀JA | Thermal Resistance Junction-ambient ¹ | 63 | °C/W |
| ReJC | Thermal Resistance Junction-Case ¹ | 1.46 | °C /W |

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Electrical Characteristics (T_J=25℃, unless otherwise noted)

| Symbol | Parameter | Conditions | Min. | Тур. | Max. | Unit |
|------------|--|--|------|-------|------|------|
| BVDSS | Drain-Source Breakdown Voltage | Vgs=0V , Ip=250uA | 68 | 72 | | V |
| △BVDSS/△TJ | BVDSS Temperature Coefficient | Reference to 25℃, I _D =1mA | | 0.023 | | V/°C |
| RDS(ON) | Static Drain-Source On-Resistance ² | Vgs=10V , Ip=10A | | 7.5 | 9.0 | mΩ |
| VGS(th) | Gate Threshold Voltage | Vgs=Vps , Ip =250uA | 2.0 | 3.0 | 4.0 | V |
| △VGS(th) | V _{GS(th)} Temperature Coefficient | VGS=VDS , ID =250UA | | -4.2 | | mV/℃ |
| IDSS | Drain-Source Leakage Current | Vps=68V , Vgs=0V , TJ=25℃ | | | 1 | uA |
| 1000 | | V _D s=68V , V _G s=0V , T _J =55℃ | | | 5 | |
| IGSS | Gate-Source Leakage Current | Vgs=±20V , Vps=0V | | | ±100 | nA |
| Qg | Total Gate Charge (4.5V) | | | 35 | | nC |
| Qgs | Gate-Source Charge | VDS =30V, ID =30A, VGS =10V | | 11 | | |
| Qgd | Gate-Drain Charge | 100 101 | | 9 | | |
| Td(on) | Turn-On Delay Time | VDS =30V,ID =30A, | | 15 | | |
| Tr | Rise Time | | | 90 | | ns |
| Td(off) | Turn-Off Delay Time | RGEN =3Ω, V GS =10V | | 45 | | |
| Tf | Fall Time | | | 30 | | |
| Ciss | Input Capacitance | | | 4000 | | |
| Coss | Output Capacitance | V _{DS} =15V , V _{GS} =0V , f=1MHz | | 267 | | pF |
| Crss | Reverse Transfer Capacitance | | | 250 | | |
| IS | Continuous Source Current ^{1,5} | | | | 80 | Α |
| ISM | Pulsed Source Current ^{2,5} | V _G =V _D =0V , Force Current | | | 320 | Α |
| VSD | Diode Forward Voltage ² | V GS =0V, I S =80A | | | 1.2 | V |
| trr | Reverse Recovery Time | T J =25℃ | | 78 | | nS |
| Qrr | Reverse Recovery Charge | I F =20A,dI/dt=100A/μs | | 51 | | nC |

Note:

- 1. The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- $\ensuremath{\mathsf{2}}_{\ensuremath{\mathsf{N}}}$ The data tested by pulsed , pulse width .The EAS data shows Max. rating .
- 3 . The test cond \leq 300us duty cycle \leq 2%, duty cycle ition is TJ =25°C, VDD =35V, VG =10V, R G =25 Ω , L=0.5mH, IAS =21A

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- 4. The power dissipation is limited by 175°C junction temperature
- 5. The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

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Typical Characteristics

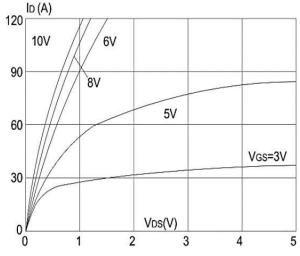


Figure1: Output Characteristics

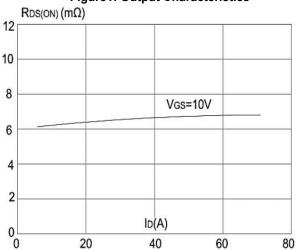


Figure 3:On-resistance vs. Drain Current

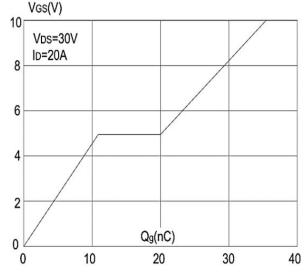


Figure 5: Gate Charge Characteristics

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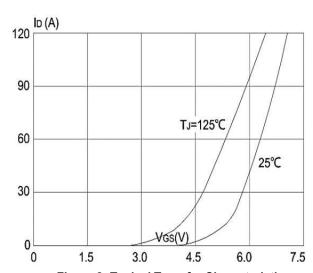


Figure 2: Typical Transfer Characteristics

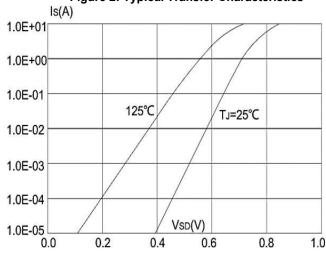


Figure 4: Body Diode Characteristics

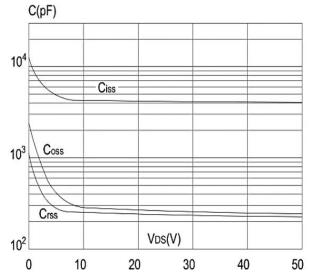


Figure 6: Capacitance Characteristics





Typical Characteristics

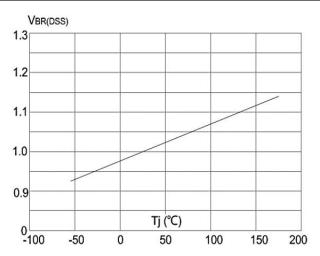


Figure 7: Normalized Breakdown Voltage vs Junction Temperature

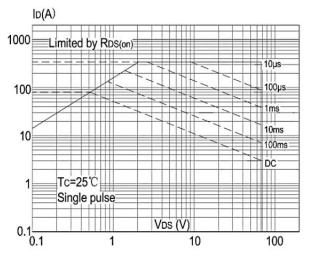


Figure 9: Maximum Safe Operating Area

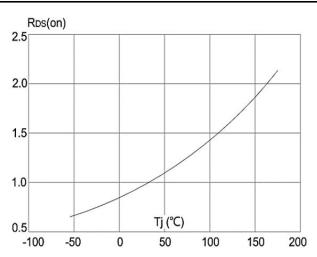


Figure 8: Normalized on Resistance vs.

Junction Temperature

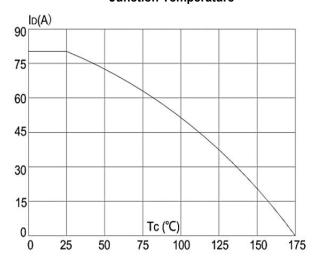


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

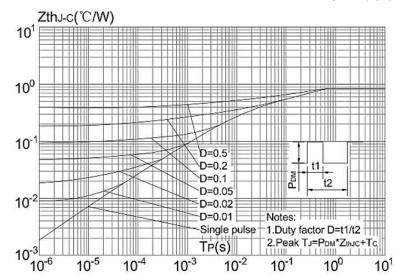
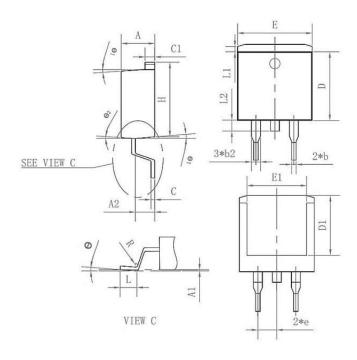


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambien



Package Mechanical Data-TO-263-3L-SLK



| | Common | | | |
|--------|--------|-------|-------|--|
| Symbol | mm | | | |
| | Mim | Nom | Max | |
| Α | 4.35 | 4.47 | 4.60 | |
| A1 | 0.09 | 0.10 | 0.11 | |
| A2 | 2.30 | 2.40 | 2.70 | |
| b | 0.70 | 0.80 | 1.00 | |
| b2 | 1.25 | 1.36 | 1.50 | |
| С | 0.45 | 0.50 | 0.65 | |
| C1 | 1.29 | 1.30 | 9.40 | |
| D | 9.10 | 9.20 | 9.30 | |
| D1 | 7.90 | 8.00 | 8.10 | |
| E | 9.85 | 10.00 | 10.20 | |
| E1 | 7.90 | 8.00 | 8.10 | |
| Н | 15.30 | 15.50 | 15.70 | |
| е | - | 2.54 | - | |
| L | 2.34 | 2.54 | 2.74 | |
| L1 | 1.00 | 1.10 | 1.20 | |
| L2 | 1.30 | 1.40 | 1.50 | |
| R | 0.24 | 0.25 | 0.26 | |
| θ | 0° | 4° | 8° | |
| Θ1 | 4° | 7° | 10° | |
| Θ2 | 0° | 3° | 6° | |

Package Marking and Ordering Information

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|--|-----------|---------|----------|--|
| Product ID | Pack | Marking | Qty(PCS) | |
| TAPING | TO-263-3L | | 800 | |

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